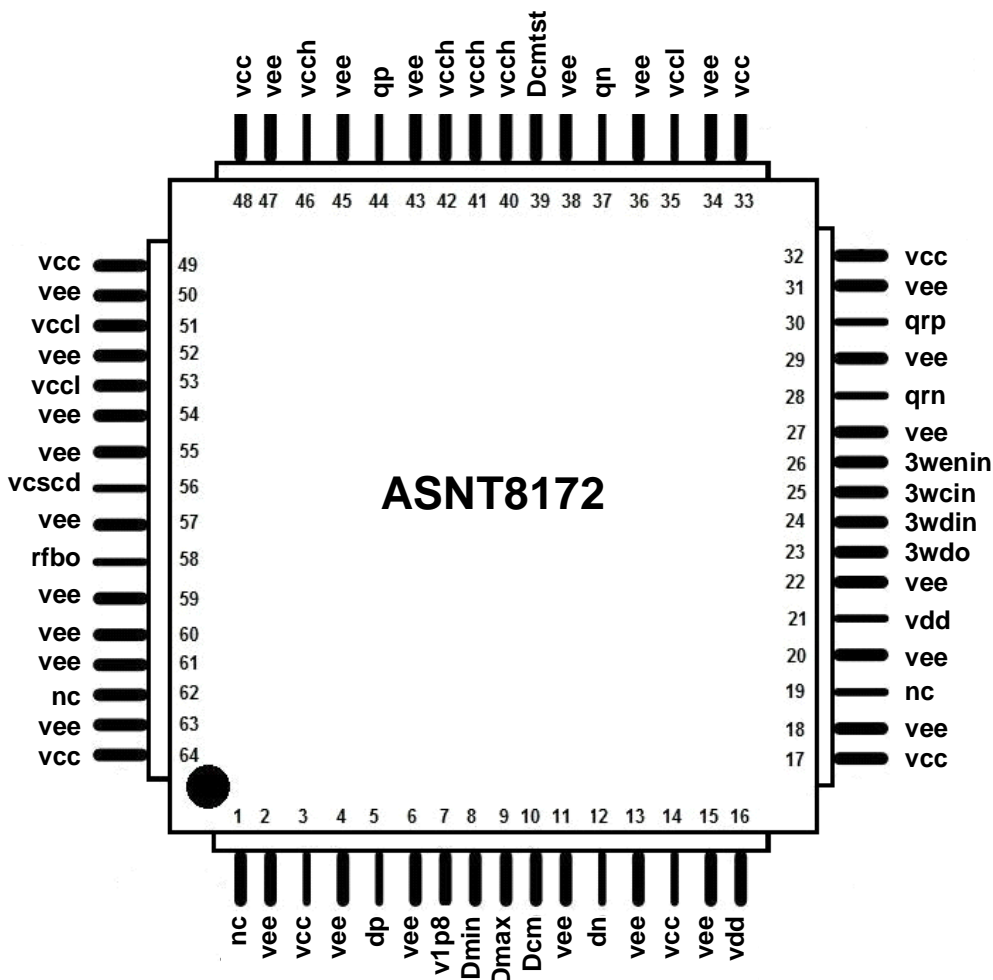




## ASNT8172-KMF 2V Driver with Asynchronous Finite Impulse Response Filter

- DC to 10GHz 9-tap finite impulse response filter (FIR)
- One differential digital CML input port
- One differential analog output port
- 6-bit tap gain and tap peaking controls
- 3-bit additional gain control for initial FIR calibration using a tap replica
- 4-bit output buffer gain and 6-bit output buffer peaking controls
- 3-wire SPI for loading all control values
- Three positive power supplies
- Maximum power consumption: 1.24W
- Custom CQFP 64-pin package





## DESCRIPTION

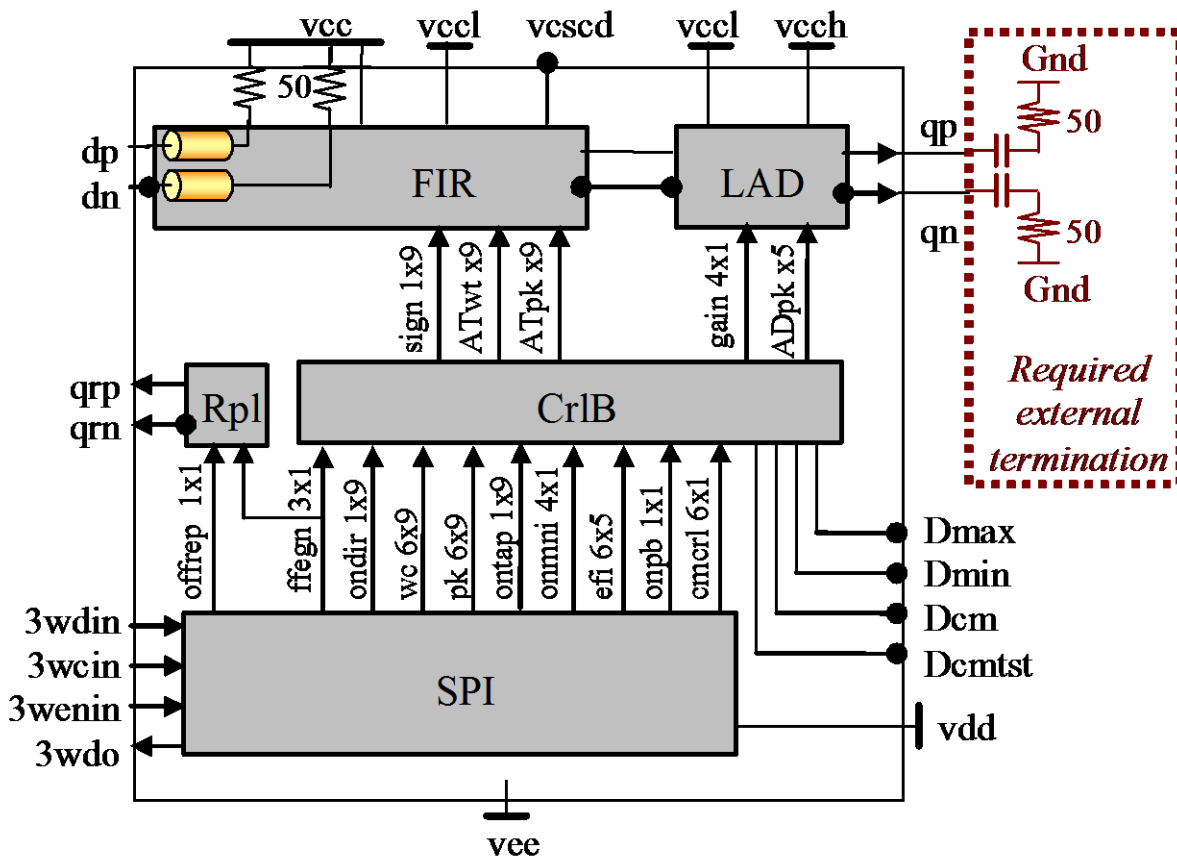


Fig. 1. Functional Block Diagram

The IC shown in Fig. 1 is a differential driver with an externally controlled 9-tap pre-emphasis. It receives a high-speed binary data signal through its differential input port **dp/dn**. The FIR block processes the input signal in accordance with nine pre-defined filter coefficients to perform the pre-emphasis operation. The resulting analog signal is amplified by a linear amplifier-driver LAD, and delivered to the output linear differential port **outp/outn** that operates in ECL-type mode and requires external  $50\Omega$  AC terminations. If DC terminations are desired, a special external resistor network should be designed.

All chip functions are controlled through a 3-wire serial-to-parallel interface (SPI) that operates in combination with an internal control block CrIB.

The chip includes a 1-tap replica Rpl that can be independently enabled and used for initial gain calibration as described below.

### FIR

The FIR block includes 8 dual transmission lines for direct and inverted input data signals with a single-ended impedance of  $50\Omega$  and matching internal terminations to **vcc** at their ends. Signals from all 9 nodes are processed by tap buffers to deliver 9 delayed copies of the differential input signal with controlled signs and weights to a summation point. The signs and weights are defined by internal binary signals **sign** and analog signals **ATwt** respectively. In addition, frequency response (peaking) of each tap can be adjusted using internal



analog signals  $ATpk$ . The weight of any tap #X can be reduced to exact 0 by a 1-bit digital signal  $ontapX='0'$ , or can be controlled normally with  $ontapX='1'$  as described below in CrIB.

FIR requires initial calibration after which it delivers an optimal signal to its output. The calibration is performed using a replica block (Rpl) that is described below.

## LAD

LAD amplifies the analog signal from FIR, and delivers it to the differential output port  $outp/outn$ . This port operates in ECL-type mode as a current source/sink and requires external  $50\Omega$  AC terminations. A DC termination scheme is also possible but requires an external resistor network.

The gain and frequency response (peaking) of LAD can be adjusted using internal 4-bit binary signal  $gain$ , and six analog signals  $ADpk$  respectively. The LAD's internal buffer with the gain adjust functionality includes a cascode stage for better performance. The reference voltage for the cascode stage can be monitored and adjusted through a control port  $vcscd$  to achieve the best output signal.

## CrIB

This control block converts binary signals from SPI into binary, and analog control signals delivered to FIR, LAD, and Rpl.

There are 45 input binary signals to CrIB from SPI, 10 output binary signals, and 23 output analog signals from CrIB. Their logic relations are detailed in Table 1.

Table 1. Control Signals

Output	To	Bits	Signals	Input 1	Bits	Operation	Input 2	Bits	Operation	Input 3	Bits
signX	FIR	1	9	ondirX	1						
ATwtX	FIR	-	9	wcX	6	AND	ontapX	1	AND	ffegn	3
ATpkX	FIR	-	9	pkX	6	AND	ontapX	1	AND	ffegn	3
gain	LAD	4	1	onmni	4	AND	onpb	1			
ADpkX	LAD	-	5	efi	6						
Internal DAC threshold adjustment				cmcr1	6						

The value of  $ondirX='1'$  corresponds to a positive gain of tap #X. The minimum value of  $wcX=0$  corresponds to a tap #X gain close to 0. The exact 0 gain value for the tap #X is achieved in case of  $ontapX='0'$ . The maximum value of  $wcX=63$  corresponds to the nominal gain of tap #X specified in ELECTRICAL CHARACTERISTICS. The initial calibration of this nominal gain should be performed as described in Rpl. The maximum value of  $pkX=63$  corresponds to maximum bandwidth (and peaking) in the tap #X.

The minimum value of  $onmni=0$  corresponds to a LAD gain close to 0. The exact 0 gain value for LAD is achieved in case of  $onpb='0'$ . The maximum value of  $onmni=7$  corresponds to the highest gain of LAD. The optimal value of LAD gain depends on the fabrication process variations, and should be defined by the nominal output swing specified in ELECTRICAL CHARACTERISTICS. The maximum value of  $efi=63$  corresponds to maximum bandwidth (and peaking) in LAD.

LAD also provides signals to 4 external analog ports for monitoring of its internal DAC operation as shown in Table 2.



Table 2. DAC Monitoring Signals

Output signal	Function	Input signal
Dmax	Maximum DAC output signal	Constant 111111 DAC input
Dmin	Minimum DAC output signal	Constant 000000 DAC input
Dcm	DAC threshold	cmcr1
Dcmst	DAC threshold before downshift	cmcr1

The values of Dmax and Dmin must be within the ranges specified in ELECTRICAL CHARACTERISTICS. The value of Dcm should be equal to (Dmux+Dmin)/2. Dcm is a downshifted copy of Dcmst, and both values can be adjusted by a 6-bit signal cmcr1 delivered through SPI. This adjustment of internal DAC thresholds is required for the correct generation of internal differential control signals.

## Rpl

The tap replica Rpl can be used for initial tap gain calibration to ensure the optimal maximum data signal swing at the FIR output over process variations.

Rpl is an exact copy of one tap operating at its maximum weight. In the optimal state, it should generate a predefined DC voltage difference between its outputs qrp and qrn. This difference may be adjusted using the 3-bit binary signal ffegn. The same signal is used to adjust the ATwtX and ATpkX analog signals applied to actual taps as shown in Table 1. Rpl is used for initial calibration only, and can be completely disabled by the binary signal offrep="1".

## SPI

3-wire SPI operates in slave mode and accepts three CMOS signals: 3wenin (SSn), 3wcin (SCLK), and 3wdin (MOSI) as described in ELECTRICAL CHARACTERISTICS. Additional CMOS data output 3wdo (MISO) is provided for control purposes.

SPI converts 25 input serial bytes into 45 parallel binary control signals delivered to Cr1B, and one binary signal to Rpl. The input package description is presented in Table 3.

Table 3. Control Bytes

Byte No.	Signal 1		Signal 2		Signal 3		Byte No.	Signal 1		Signal 2		Signal 3	
	Name	Bit #	Name	Bit#	Name	Bit#		Name	Bit #	Name	Bit#	Name	Bit#
1	ontap1	7	ondir1	6	wc1	5-0	14	pk7	7-2	empty	1	empty	0
2	pk1	7-2	empty	1	empty	0	15	ontap8	7	ondir8	6	wc8	5-0
3	ontap2	7	ondir2	6	wc2	5-0	16	pk8	7-2	empty	1	empty	0
4	pk2	7-2	empty	1	empty	0	17	ontap9	7	ondir9	6	wc9	5-0
5	ontap3	7	ondir3	6	wc3	5-0	18	pk9	7-2	empty	1	empty	0
6	pk3	7-2	empty	1	empty	0	19	efi0	7-2	empty	1	empty	0
7	ontap4	7	ondir4	6	wc4	5-0	20	efi1	7-2	empty	1	empty	0
8	pk4	7-2	empty	1	empty	0	21	efi2	7-2	empty	1	empty	0
9	ontap5	7	ondir5	6	wc5	5-0	22	efi3	7-2	empty	1	empty	0
10	pk5	7-2	empty	1	empty	0	23	efi4	7-2	empty	1	empty	0
11	ontap6	7	ondir6	6	wc6	5-0	24	cmcr1	7-2	offrep	1	empty	0
12	pk6	7-2	empty	1	empty	0	25	ffegn	7-5	onpb	4	onmni	3-0
13	ontap7	7	ondir7	6	wc7	5-0							



The bytes are delivered starting from 1 to 25 and bits within a byte are delivered starting from MSB. Bit#7 is the MSB of a byte as shown in Fig. 2. Internal registers are updated at a rising edge of 3wenin.

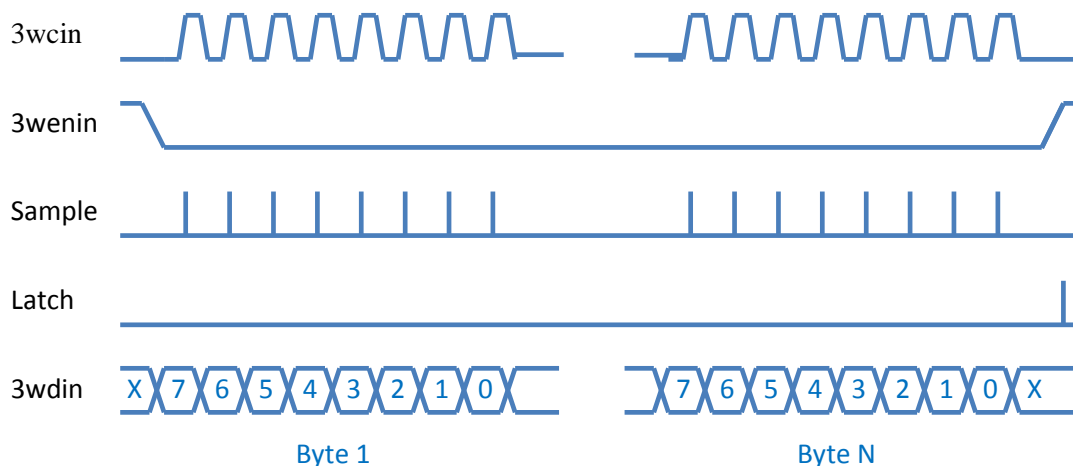


Fig. 2. SPI Operation

The FIR block is designed in such a way that it requires normalization of tap gains. Assuming that  $w_{C_{MAX}}$  equals 63 (or 111111 in binary code), the tap weight control binary signals  $w_{C_X}$  supplied to the SPI should be

softly normalized to satisfy the equation  $\sum_{i=1}^9 |w_{C}(i)| \leq w_{C_{MAX}}$ .

## POWER SUPPLY CONFIGURATION

The IC requires four positive external power supplies. The first supply  $v_{CC}$  is used for the data input terminations, and to power all high-speed digital circuitry and reference sources. The second supply  $v_{CC1}$  powers the internal analog circuitry. The third supply  $v_{CC2}$  is used for the output analog driver. The digital supply  $v_{DD}$  is used for the internal CMOS circuits of the SPI.

All supplies are positive in relation to the internal common node  $v_{EE}=0.0V$ .

## ABSOLUTE MAXIMUM RATINGS

Caution: Exceeding the absolute maximum ratings may cause damage to this product and/or lead to reduced reliability. Functional performance is specified over the recommended operating conditions for power supply and temperature only. AC and DC device characteristics at or beyond the absolute maximum ratings are not assumed or implied. All min and max voltage limits are referenced to ground.

Table 4. Absolute Maximum Ratings

Parameter	Min	Max	Units
Supply Voltages ( $v_{CC}$ , $v_{CC1}$ , $v_{CC2}$ , $v_{DD}$ )		3.0, 4.0, 8.0, 1.5	V
Power Consumption		1.5	W
Case Temperature		+90	°C
Storage Temperature	-40	+100	°C
Operational Humidity	10	98	%
Storage Humidity	10	98	%



## TERMINAL FUNCTIONS

TERMINAL			Description
Name	No.	Type	
<b>High-Speed I/Os</b>			
dp	5	CML-type input	Differential high-speed data inputs with internal SE 50 $\Omega$ terminations to VCC
dn	12		
qp	44	ECL-type output	Differential high-speed data outputs; require external SE 50 $\Omega$ AC terminations
qn	37		
<b>Low-Speed I/Os</b>			
3wenin	26	1.2V CMOS input	Enable input signal SSn for 3-wire interface
3wcin	25		Clock input signal SCLK for 3-wire interface
3wdin	24		Data input signal MOSI for 3-wire interface
3wdo	23	1.2V CMOS output	Data output signal MISO for 3-wire interface
<b>Analog Control Voltages</b>			
v1p8	7	Internal voltage generator output	Internal voltage source of vee+1.8V
vcsd	56		Internal voltage source of vcch-4.0V
rfbo	58		Internal voltage reference node
<b>Analog Control Nodes (for DMM measurements only!)</b>			
Dmin	8	Analog DC output	DAC minimum output indicator
Dmax	9		DAC maximum output indicator
Dcm	10		DAC common-mode output indicator
Dcmtst	39		DAC control output with internal 12.4 $\Omega$ termination to VCC
qrp	30		Replica differential data outputs with internal SE 42 $\Omega$ terminations to VCC
qrn	28		

<b>Supply And Termination Voltages</b>		
Name	Description	Pin Number
vee	External ground	2, 4, 6, 11, 13, 15, 18, 20, 22, 27, 29, 31, 34, 36, 38, 43, 45, 47, 50, 52, 54, 55, 57, 59, 60, 61, 63
vcc	Positive power supply (HS digital part)	3, 14, 17, 32, 33, 48, 49, 64
vccl	Positive power supply (analog part)	35, 51, 53
vcch	Positive power supply (output driver)	40-42, 46
vdd	Positive power supply (digital control part)	16, 21
nc	not connected pins	1, 19, 62



## ELECTRICAL CHARACTERISTICS

PARAMETER	MIN	TYP	MAX	UNIT	COMMENTS
<b>General Parameters</b>					
vcc		2.6		V	High-speed digital supply
vccl		3.5		V	Analog supply
vcch		7.5		V	Analog supply
vdd		1.2		V	CMOS digital supply
vee		0.0		V	External ground
Ivcc		43		mA	
Ivccl		40		mA	
Ivcch		132		mA	
Power consumption		1.24		W	
Junction temperature	-25	50	125	°C	
<b>FIR Parameters</b>					
No. of Taps		9			
Delay between Taps		11		ps	
Voltage gain		3.5		dB	From chip input to FIR output, can be verified by Rpl measurements
<b>High Speed Input Data (dp/dn)</b>					
Data Rate	DC		20	Gb/s	
Swing		220		mV	Differential or SE, p-p
S11		TBD		dB	
CM Voltage Level		vcc		V	Must match for both inputs
<b>Analog Output Data (qp/qn)</b>					
Bandwidth	DC		10	GHz	
Swing		1200		mV	on each SE output
S22		TBD		dB	
CM Voltage Level		2.4		V	
<b>DC Control Voltages</b>					
v1p8	vee+1.85	vee+1.75		V	
vcscd	vcch-4.1	vcch-3.9		V	
qrp-qrn		330		mV	with optimal ffegn
Dmax	vcc-0.9	vcc-0.7		V	Should be always Dmax-Dmin=0.4±0.05
Dmin	vcc-1.3	vcc-1.1		V	
Dcm	vcc-1.1	vcc-0.9		V	Should be Dcm=(Dmux+Dmin)/2
Dcmst	vcc-0.25	vcc-0.15		V	
<b>3-Wire Interface Ports</b>					
Clock frequency			6	MHz	
Low logic level		0		V	
High logic level		1.2		V	

## PACKAGE INFORMATION

The chip die is housed in a custom 64-pin CQFP package. The dimensioned drawings are shown in Fig. 3. The package provides a center heat slug located on its back side to be used for heat dissipation. ADSANTEC recommends for this section to be soldered to the **vee** plain, which is ground for a positive supply.

The part's identification label is ASNT8172-KMF. The first 8 characters of the name before the dash identify the bare die including general circuit family, fabrication technology, specific circuit type, and part version while the 3 digits after the underscore represent the package's manufacturer, type, and pin out count.

This device complies with the Restriction of Hazardous Substances (RoHS) per 2011/65/EU for all ten substances.

### 64-PIN KMF Package

All Dimensions are in millimeters

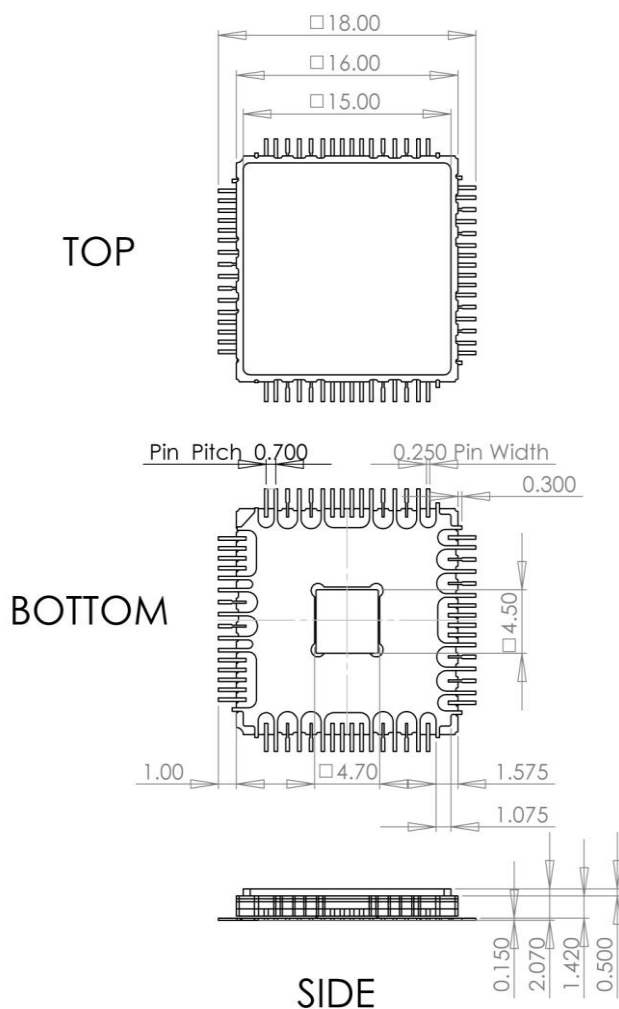


Fig. 3. CQFP 64-Pin Package Drawing (All Dimensions in mm)





## REVISION HISTORY

Revision	Date	Changes
1.2.2	05-2020	Updated Package Information
1.1.2	07-2019	Updated Letterhead
1.1.1	08-2017	Corrected terminal functions section Corrected electrical characteristics section Corrected package information section
1.0.1	05-2017	Initial Release